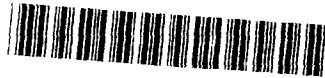


08-16-2004



HEET

102814280

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Masaaki Iwasaki

8.604

2. Name and address of receiving party(ies):

Tyco Electronics AMP K.K.
3-5-8, Hisamoto, Takatsu-ku,
Kawasaki-shi, Kanagawa-ken 213-8535
JAPAN

19249 U.S. PTO
10/913198



Additional name(s) & address(es) attached Yes No

Additional name(s) & address(es) attached Yes No

3. Nature of conveyance: Assignment Merger Security Agreement Change of Name

Execution Date: May 18, 2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: May 18, 2004

A. Patent Application No.(s):

Unknown

B. Patent No.(s):

Filing Date: Herewith

5. Name and address of party to whom correspondence concerning document should be mailed:

Barley Snyder, LLC
1000 Westlakes Drive, Suite 275
Berwyn, PA 19312

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h)) \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit Account #501581

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments, and document: 3

Steven E. Bach
Registration No. 46,530
Attorney for Applicant
Phone: (610) 889-3697
Date: August 6, 2004

08/13/2004 ECDOPER 00000010 10913198

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40.00 00

Express Mail No. EV394975608US
Docket No. 21334-1352

ASSIGNMENT

I/We, Masaaki Iwasaki

who reside at

Kanagawa, Japan

have made certain inventions or discoveries (or both) set forth in an application for Letters Patent of the United States of America entitled:

SURFACE MOUNTING CONNECTOR

which application was executed by the inventor(s) on the date(s) or execution of this assignment and is identified by Tyco Electronics AMP K.K. File Number **51619** and **Japanese Patent Application No. 2003-287881** filed on **August 6, 2003**.

and Tyco Electronics AMP K.K.

whose address is 3-5-8, Hisamoto, Takatsu-ku, Kawasaki-shi, Kanagawa-ken 213-8535, Japan

and which, together with its successors and assigns is hereinafter called "Assignee", is desirous of acquiring the title, rights, benefits and privileges hereinafter recited, and of confirming the same or any part thereof heretofore acquired by Assignee.

Now, therefore, for valuable consideration furnished by Assignee to me/us, receipt and sufficiency of which I/we hereby acknowledge, I/we hereby, without reservation:

1. Assign and convey to and confirm in Assignee the entire right, title and interest in and to said inventions and discoveries, said patent application in Japan, any and all other applications for Letters Patent on said inventions and discoveries in whatsoever countries, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or discoveries or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions and discoveries or upon said applications, and every priority right that is or may be predicted upon or arise from said inventions, said discoveries, said applications, and said Letters Patent;

2. Authorize Assignee to file patent applications in any or all countries on any or all of said inventions and discoveries in my/our names or in the name of Assignee or otherwise as Assignee may deem advisable, under the International Convention or otherwise;

3. Authorize and request the empowered officials of all governments to issue or transfer all said Letters Patent to Assignee, as assignee of the entire right, title and interest therein or otherwise as Assignee may direct:

4. Warrant that I/we have not knowingly conveyed to others any right in said inventions, discoveries, applications or patents or any license to use the same or to make, use or sell anything embodying or utilizing any or said inventions or discoveries; and that I/we have good right to assign the same to Assignee without encumbrance;

5. Bind my/our heirs and legal representatives, as well as myself/ourselves, to do, upon Assignee's request and at its expense, but without additional consideration to me/us or them, all acts reasonably serving to assure that the said inventions and discoveries, the said patent applications and the said Letters Patent shall be held and enjoyed by Assignee as fully and entirely as the same could have been held and enjoyed by me/us or my/our heirs or representatives if this assignment had not been made; and particularly to execute and deliver to Assignee all lawful application documents including petitions, specifications, and oaths, and all assignments, disclaimers, and lawful affidavits in form and substance as may be requested by Assignee; to communicate to Assignee all facts known to me relating to said inventions and discoveries or the history thereof; and to furnish Assignee with any and all documents, photographs, models, samples and other physical exhibits in my/our control or in the control of my/our control or in the control of my/our heirs or legal representatives and which may be useful for establishing the facts of my conceptions, disclosure, and reduction to practice of said inventions and discoveries.

The effective date of this instrument is July 25, 2003.

It testimony whereof I/we affixed my/our signature(s).

Tadahiro Fuyukura 18 MAY 04
(Witness) (Date)

Masaaki Iwasaki 18 MAY 04
(Inventor)Masaaki Iwasaki (Date)

Takafumi Kubo 18 MAY 04
(Witness) (Date)